

STMP3770XXBJEA2N

(Not Recommended for New Designs)

PMP CONTROLLER

Package

[VFBGA100](#)

VFBGA100, plastic, very thin fine-pitch ball grid array; 100 balls; 0.5 mm pitch; 6 mm x 6 mm x 0.66 mm body



Image not available

[Buy Options](#) | [Operating Characteristics](#) | [Environmental Information](#) | [Quality Information](#) | [Shipping Information](#)

Buy Options

STMP3770XXBJEA2N
935317037557
NOT RECOMMENDED FOR NEW DESIGNS

TRAY-Tray, Bakeable, Multiple in Drypack
Min. Package Quantity: 429
Lead Time: 15 weeks

Operating Characteristics

No information available

Environmental Information

Material Declaration	Pb-Free	EU RoHS	Halogen Free	RHF Indicator	2nd Level Interconnect	REACH SVHC	Weight (mg)
STMP3770XXBJEA2N (935317037557)	Yes	Yes	Yes	D	e1	REACH SVHC	64.6

Quality Information

Material Declaration	Safe Assure Functional Safety	Moisture Sensitivity Level (MSL)	Peak Package Body Temperature (PPT) (C°)	Maximum Time at Peak Temperatures (s)
	Lead Free Soldering	Lead Free Soldering	Lead Free Soldering	Lead Free Soldering
STMP3770XXBJEA2N (935317037557)	No	3	260	40

Shipping Information

Part Number	Harmonized Tariff (US) Disclaimer	Export Control Classification Number (US)
STMP3770XXBJEA2N (935317037557)	854231	5A992

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